

修订记录 / Revised record

描述 / Descriptions

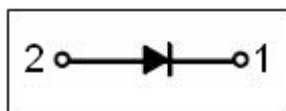
SOD-323

Schottky Diode in a SOD-323 Plastic Package.

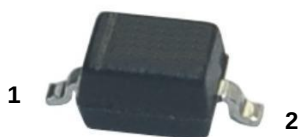
特征 / Features

用途 / Applications

内部等效电路 / Equivalent Circuit

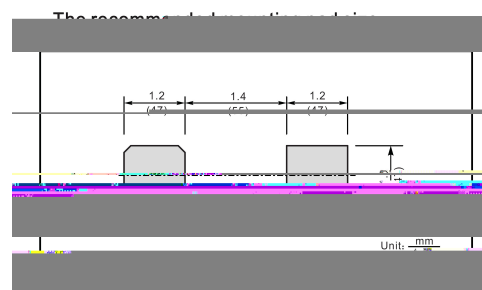


引脚排列 / Pinning



PIN1:Cathode

PIN2:Anode



放大及印章代码 / h_{FE} Classifications & Marking

Model	RB501V-40
Marking	4

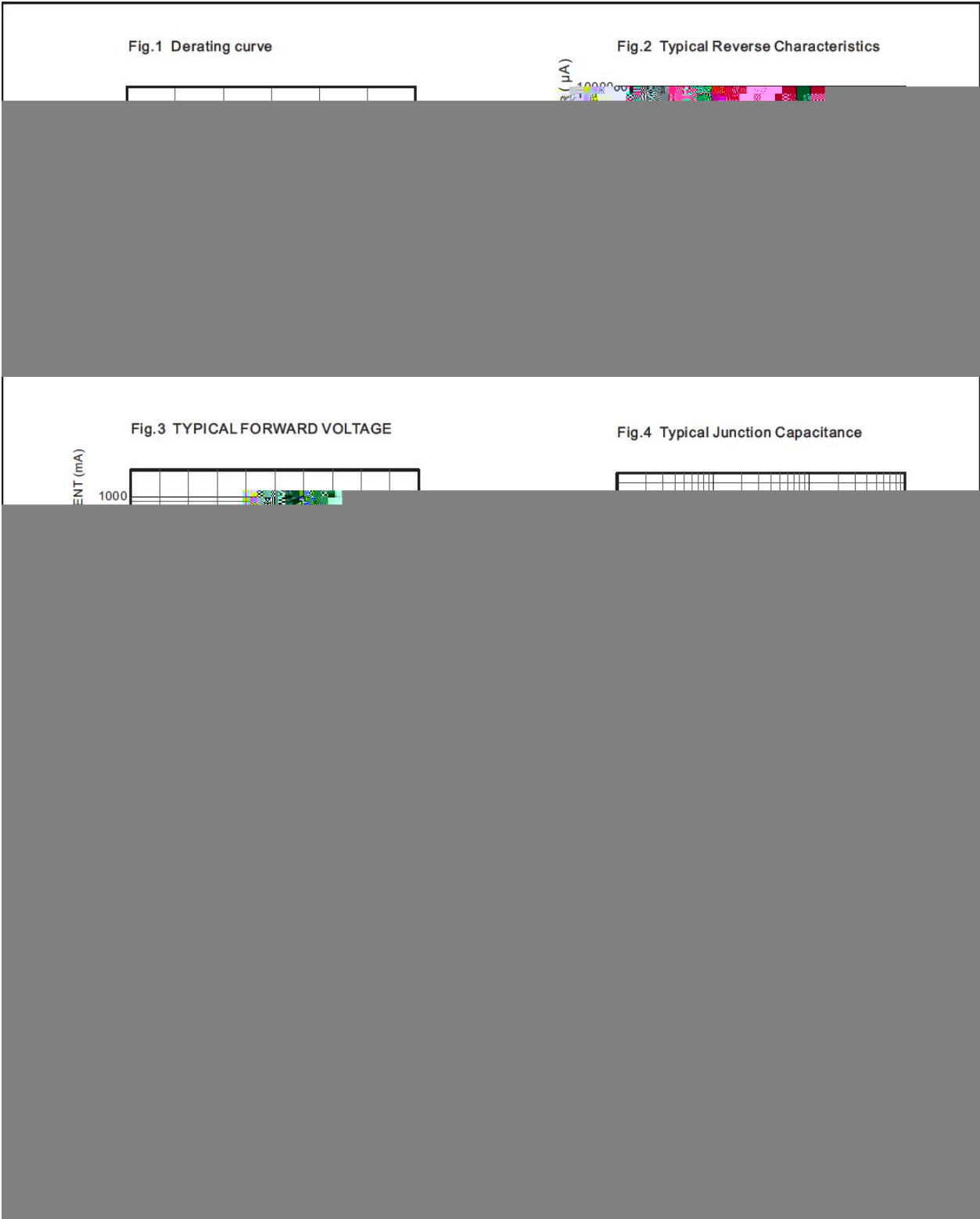
极限参数 / Absolute Maximum Ratings(Ta=25°C)

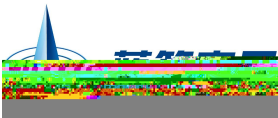
Parameter	Symbol	Rating	Unit
Maximum recurrent peak reverse voltage	V_{RM}	45	V
DC reverse voltage	V_R	40	V
Continuous forward current	I_O	0.1	A
Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	13	A
Capacitance between terminals $V_R=10V, f=1MHz$	C_T	6	pF
Junction Temperature	T_j	125	°C
Storage Temperature	T_{stg}	-55 ~ +150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

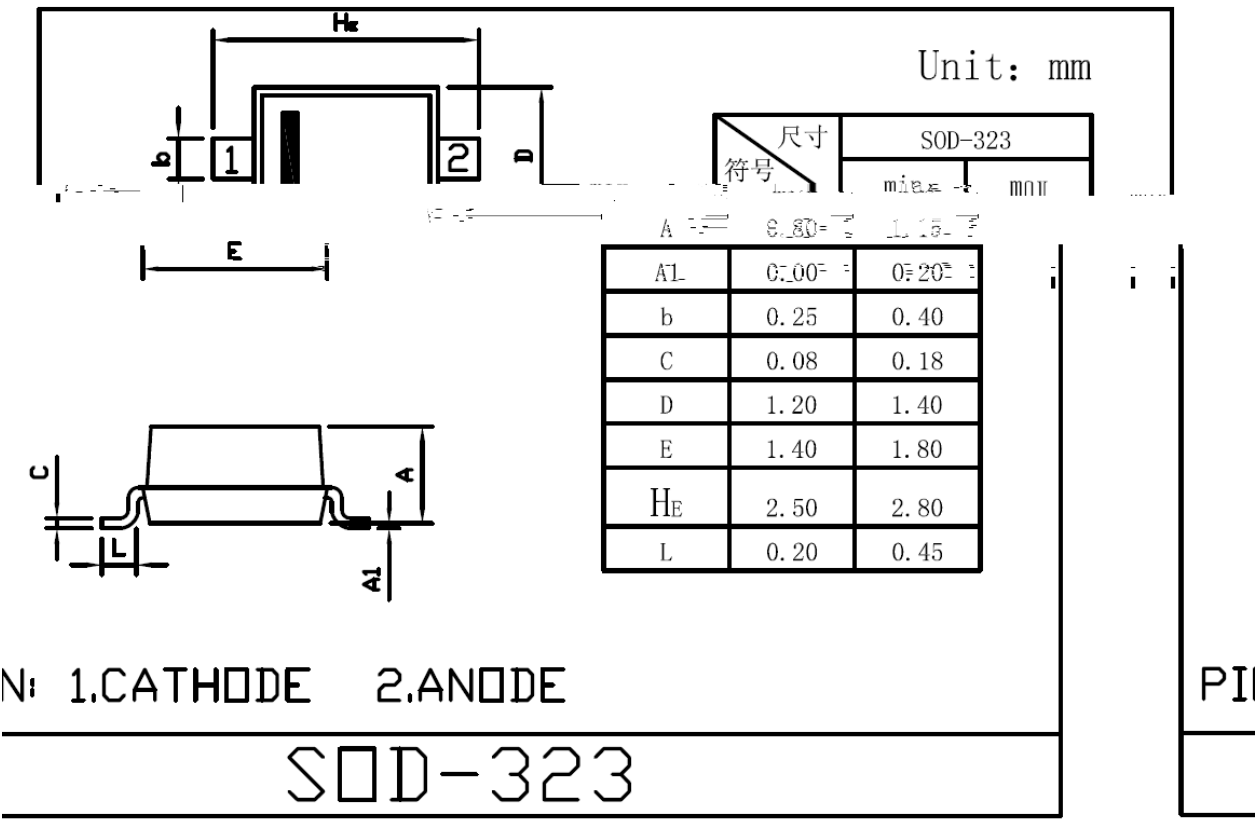
Parameter	Symbol	Test Conditions	Rating	Unit
Maximum Forward Voltage	V_F	$I_F=10mA$	0.34	V
		$I_F=100mA$	0.55	
Reverse Leakage Current	I_R	$V_R=10V$	30	uA

电参数曲线图 / Electrical Characteristic Curve

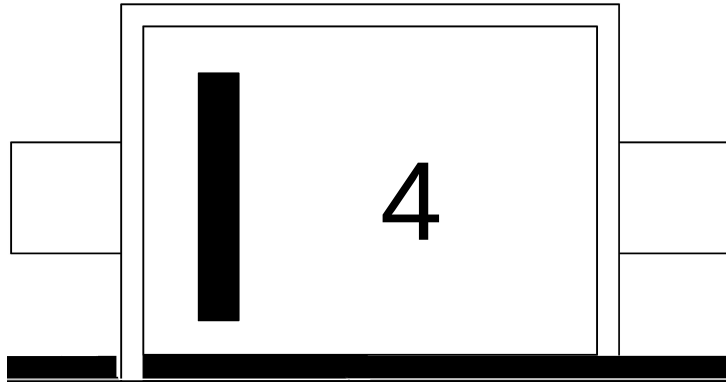




外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions

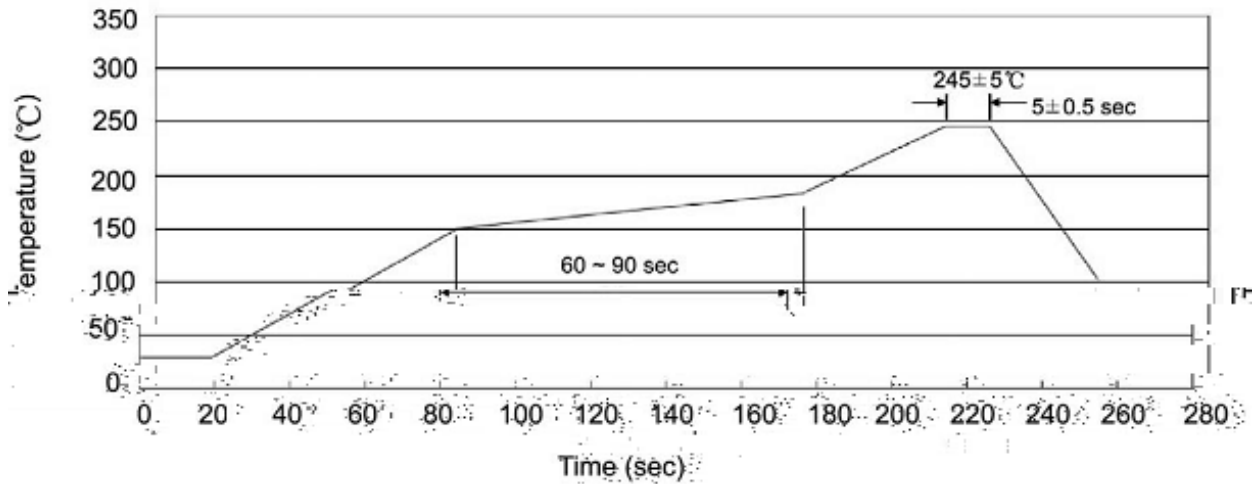


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Note:

4 : Product Type.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
SOD-323	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205

使用说明 / Notices